Suppliment tal-Gazzetta tal-Gvern ta' Malta Nru. 21,702, 14 ta' Awwissu, 2026
Taqsima B

L.N. 222 of 2026

PRODUCT SAFETY ACT (CAP. 427)

Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (Amendment) Regulations, 2026

IN EXERCISE of the powers conferred by articles 38 and 39 of the Product Safety Act, the Minister responsible for consumer affairs, on the advice of the Director General (Technical Regulations), has made the following regulations:-

Citation and scope.

S.L. 427.57.

1. (1) The title of these regulations is the Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (Amendment) Regulations, 2026, and these regulations shall be read and construed as one with the Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment Regulations, hereinafter referred to as the "principal regulations".

(2) The scope of these regulations is to transpose:

(a) Commission Delegated Directive (EU) 2025/1802 of 8 September 2025 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in high melting temperature solders;

(b) Commission Delegated Directive (EU) 2025/2363 of 8 September 2025 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in glass or ceramic components;

(c) Commission Delegated Directive (EU) 2025/2364 of 8 September 2025 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead as an alloying element in steel, aluminium and copper; and

(d) Corrigendum to Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Amends regulation 7 of the principal regulations.

2. In paragraph (b) of regulation 7 of the principal regulations the words "regulation 5*(f)* and *(g)*" shall be substituted by the words "regulations 5(g) and 5(h)".

Amends Schedule III to the principal regulations.

3. Schedule III to the principal regulations shall be amended as follows:

(a) items 6(a) and 6(a)-I thereof shall be substituted by the following new items:

"6(a)	Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight	Expires on 11 December 2026.
6(a)-I	Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight (*)	Expires on 30 June 2027 for all categories.";

(b) immediately after item 6(a)-I thereof, as substituted, there shall be added the following new item:

"6(a)-II	Lead as an alloying element in batch hot-dip galvanised steel components containing up to 0,2 % lead by weight (*)	Expires on 30 June 2027 for all categories.";

(c) items 6(b), 6(b)-I and 6(b)-II thereof shall be substituted by the following new items:

"6(b)	Lead as an alloying element in aluminium containing up to 0,4 % lead by weight	Expires on 11 June 2027.
6(b)-I	Lead as an alloying element in aluminium containing up to 0,4 % lead by weight, provided it stems from lead-bearing aluminium scrap recycling (*)	Expires on 11 December 2026 for categories 1-7, 10. Expires on 30 June 2027 for categories 9 industrial monitoring and control instruments, and 11.
6(b)-II	Lead as an alloying element in aluminium for machining purposes with a lead content up to 0,4 % by weight (*)	Expires on 11 June 2027 for categories 1-7, 10. Expires on 30 June 2027 for categories 9 industrial monitoring and control instruments and 11 (*).";

(d) immediately after item 6(b)-II thereof, as substituted,

there shall be added the following new item:

"6(b)-III	Lead as an alloying element in aluminium casting alloys containing up to 0,3 % lead by weight provided it stems from lead-bearing aluminium scrap recycling (*)	Expires on 30 June 2027 for categories 1-8, 9 other than industrial monitoring and control instruments, and 10.";

(e) item 6(c) thereof shall be substituted by the following new item:

"6(c)	Copper alloy containing up to 4 % lead by weight (*)	Expires on 30 June 2027.";

(f) immediately after item 6(c) thereof, as substituted, there shall be added the following words:

"(*) The exemption shall not cover EEE for supply to the general public where the EEE or accessible part thereof may, during normal or foreseeable conditions of use, be placed in the mouth by children. However, the exemption shall apply where both of the following can be demonstrated:

— the rate of lead release from such an EEE or any accessible part, whether coated or uncoated, does not exceed 0,05 μg/cm^2 per hour (equivalent to 0,05 μg/g/h),

— for coated articles, that the coating is sufficient to ensure that this release rate is not exceeded for a period of at least two years of normal or reasonably foreseeable conditions of use of the EEE.

For the purpose of this footnote, it is considered that an EEE or accessible part of an EEE may be placed in the mouth by children if it is smaller than 5cm in one dimension or has a detachable or protruding part of that size.";

(g) item 7(a) thereof shall be substituted by the following

new item:

"7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	Applies to all categories (except applications covered by item 24) and expires on 30 June 2027.";

(h) immediately after item 7(a) thereof, as substituted, there shall be added the following new items:

"7(a)-I	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) for internal interconnections for attaching die, or other components along with a die in semiconductor assembly with steady state or transient/impulse currents of 0,1 A or greater or blocking voltages beyond 10 V, or die edge sizes larger than 0,3 mm × 0,3 mm	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.
7(a)-II	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) for integral (meaning internal and external) connections of die attach in electrical and electronic components, if all the following conditions are satisfied: — the thermal conductivity of the cured/sintered die-attach material is > 35 W/(m × K), — the electrical conductivity of the cured/sintered die-attach material is > 4,7 MS/m, — solidus melting temperature is higher than 260 °C	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.
7(a)-III	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) in first level solder joints (internal or integral connections – meaning internal and external) for manufacturing components so that subsequent mounting of electronic components onto subassemblies (i.e. modules, sub-circuit boards, substrates, or point-to-point soldering) with a secondary solder does not reflow the first level solder. This sub-entry excludes die attach applications and hermetic sealings	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.

7(a)-IV	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) in second level solder joints for the attachment of components to printed circuit board or lead frames: (1) in solder balls for the attachment of ceramic ball-grid array (BGA); (2) in high temperature plastic overmouldings (> 220 °C)	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.
7(a)-V	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) as a hermetic sealing material between: (1) a ceramic package or plug and a metal case; (2) component terminations and an internal sub-part	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.
7(a)-VI	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) for establishing electrical connections between lamp components in incandescent reflector lamps for infrared heating, high intensity discharge lamps, or oven lamps	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.
7(a)-VII	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) for audio transducers where the peak operating temperature exceeds 200 °C	Applies to all categories (except applications covered by item 24) and expires on 31 December 2027.

(i) items 7(c)-I and 7(c)-II thereof shall be substituted by the following new items:

"7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	Applies to all categories and expires on 30 June 2027.
7(c)-II	Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher	Applies to all categories (except applications covered by item 7(c)-I or 7(c)-IV) and expires on 31 December 2027.";

(j) immediately after item 7(c)-IV thereof there shall be added

the following new items:

"7(c)-V	Electrical and electronic components containing lead in a glass or glass matrix compound that fulfils any of the following functions: (1) for protection and electrical insulation in glass beads of high-voltage diodes and glass layers for wafers; (2) for hermetic sealing between ceramic, metal and/or glass parts; (3) for bonding purposes in a process parameter window for < 500 °C combined with a viscosity of 1 013,3 dPas ('glass-transition temperature'); (4) for use as a resistive material such as ink, with a resistivity range from 1 ohm/square to 100 megohm/square, excluding trimmer potentiometers; (5) for use in chemically modified glass surfaces for microchannel plates (MCPs), channel electron multipliers (CEMs) and resistive glass products (RGPs).	Applies to all categories and expires on 31 December 2027.
7(c)-VI	Electrical and electronic components containing lead in a ceramic that fulfils any of the following functions: (1) for use in piezoelectric lead zirconium titanate (PZT) ceramics; (2) for providing ceramics with a positive temperature coefficient (PTC).	Applies to all categories (except applications covered by items 7(c)-II, 7(c)-III and 7(c)-IV as well as item 14 of Schedule IV) and expires on 31 December 2027.".

Amends Schedule VIII to the principal regulations.

4. In Schedule VIII to the principal regulations immediately after the item "Commission Delegated Directive (EU) 2024/1416 of 13 March 2024 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for cadmium in downshifting quantum dots directly deposited on LED semiconductor chips, as applicable from 1st January 2025." there shall be added the following new items:

"- Commission Delegated Directive (EU) 2025/1802 of 8 September 2025 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in high melting temperature solders, as applicable from 1st July 2026.

- Commission Delegated Directive (EU) 2025/2363 of 8 September 2025 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in glass or ceramic components, as applicable from 1st July 2026.

- Commission Delegated Directive (EU) 2025/2364 of 8 September 2025 amending Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead as an alloying element in steel, aluminium and copper, as applicable from 1st July 2026.

- Corrigendum to Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment, as applicable from 1st July 2026.".

VERŻJONI ELETTRONIKA

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